

# PACKAGE INFORMATION

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## PACKAGE MECHANICAL CHARACTERISTICS

FOR ALL HALL DEVICE AND GTS2000 PACKAGES  
(LH, LM, LR, LT, K, KA, U, UA, SE, SG and SH PACKAGES)

Component	Material	Function	Units
Sensor Face	Thermoset epoxy	Maximum temperature	170°C <sup>2</sup>

FOR SA AND SB PACKAGES <sup>1</sup>

Component	Material	Function	Units
Sensor Face	Thermoset epoxy	Maximum temperature	170°C <sup>2</sup>
Plastic Housing	Thermoplastic PBT	264 psi deflection temp. (DTUL) 66 psi deflection temp. (DTUL) Approximate melting temperature	204°C <sup>2</sup> 216°C 225°C
Lead Pull	--	Minimum lead pull force	8 N

FOR ALL PACKAGE TYPES EXCE PT THOSE LISTED ABOVE

Component	Material	Function	Units
Package Face	Thermoset epoxy	Maximum temperature	150°C <sup>3</sup>

FOR ALL PACKAGE TYPES

Component	Material	Function	Units
Lead Finish	90% Tin / 10% Lead Solder Plating <sup>4</sup>	Thickness	300 – 800 microinches
Lead Material	Copper	--	--
Flame Class Rating	--	--	UL94V-0

<sup>1</sup> Except for the ATS630/32LSA. See the product data sheet for additional information.

<sup>2</sup> Industry-accepted soldering techniques are permitted for these packages as described in [Application Note 26009](#). If reflow soldering is required, be sure to observe the precautions for SA/SB packages listed in the "Reflow Soldering of Through-Hole Devices" section of [26009](#).

<sup>3</sup> Temperature excursions above this limit for soldering are allowed, as described in [Application Note 26009](#)

<sup>4</sup> Except for packages with "Pb-Free" finishes, which are 100% tin.